Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.051”**

**12 13 14 1 2**

**9 8 7 6 5**

**4**

**3**

**10**

**11**

**.048”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004” X .004”**

**Backside Potential:**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .048” X .051” DATE: 8/18/17**

**MFG: MOTOROLA THICKNESS .010” P/N: 5405**

**DG 10.1.2**

#### Rev B, 7/1